

B7 R23
Att C
12/13/02

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

TRADEMARK OFFICE
O I P E J C 108
DEC 18 2002
Pre Application of:
Thomas H. Osterheld
Serial No.: 09/826,419
Confirmation No.: 5039
Filed: April 5, 2001
For: Grid Relief In CMP
Polishing Pad To
Accurately Measure Pad
Wear, Pad Profile and Pad
Wear Profile

§ Group Art Unit: 3723

§ Examiner: David B. Thomas

RECEIVED

DEC 19 2002

TECHNOLOGY CENTER R3700

Commissioner for Patents
Washington, D.C. 20231

Dear Sir:

CERTIFICATE OF MAILING
37 CFR 1.8

I hereby certify that this correspondence is being deposited on
12/13/02 with the United States Postal Service
as First Class Mail in an envelope addressed to:
Commissioner for Patents, Washington, D.C. 20231

12/13/02

Date

Kent R. Miller

Signature

RESPONSE TO OFFICE ACTION DATED OCTOBER 25, 2002

In response to the Office Action dated October 25, 2002, having a shortened statutory period for response set to expire on January 25, 2003, please enter this response and reconsider the claims pending in the application for reasons discussed below. Although Applicant believes that no fee is due in connection with this response, the Commissioner is hereby authorized to charge counsel's Deposit Account No. 20-0782/AMAT/3415.Y1/CMP/CMP/RKK, for any fees, including extension of time fees or excess claim fees, required to make this response timely and acceptable to the Office.

IN THE CLAIMS:

Please amend the claims as follows:

1. (Amended) A method for measuring wear of the thickness of a chemical mechanical polishing pad, the method comprising: